

1.0 ELECTRICAL CHARACTERISTICS

1.1 Maximum Ratings*

V_{DD} 7.0V
 All inputs and outputs w.r.t. V_{SS} -0.6V to V_{DD} +1.0V
 Storage temperature -65°C to +150°C
 Ambient temp. with power applied -65°C to +125°C
 ESD protection on all pins ≥ 2 kV

***Notice:** Stresses above those listed under “Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC AND AC CHARACTERISTICS

All parameters apply at the specified temp and voltage ranges unless otherwise noted.		V _{DD} = 1.0 - 5.5V Industrial (I): -40°C to +85°C				
Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Operating Voltage Range	V _{DD}	1.0	—	5.5	V	
V _{DD} Value to RESET	V _{DDMIN}	1.0	—	—	V	
Operating Current	I _{DD}	—	45	60	μA	V _{DD} = 5.5V (no load)
V _{DD} Trip Point	MCP1X0-270 MCP1X0-300 MCP1X0-315 MCP1X0-450 MCP1X0-460 MCP1X0-475 MCP1X0-485	V _{TRIP}	2.55 2.85 3.0 4.25 4.35 4.50 4.60	2.625 2.925 3.075 4.375 4.475 4.625 4.725	2.7 3.0 3.15 4.50 4.60 4.75 4.85	V
RESET Low Level Output Voltage	MCP1X0-270 MCP1X0-300 MCP1X0-315	V _{OL}	—	—	0.4	V
	MCP1X0-450 MCP1X0-460 MCP1X0-475 MCP1X0-485		—	—	0.6	V
RESET High Level Output Voltage (MCP130 Only)	MCP130-xxx (All V _{TRIP} Points)	V _{OH}	V _{DD} -0.7	—	—	V
Pull-up Resistor (MCP130 Only)		—	5	—	kΩ	
Output Leakage (MCP120 Only)		—	1	—	μA	
Threshold Hysteresis	V _{HYS}	—	50	—	mV	
V _{DD} Detect to RESET Inactive	t _{RPU}	150	350	700	ms	
V _{DD} Detect to RESET	t _{RPD}	—	10	—	μs	V _{DD} ramped from V _{TRIPMAX} + 250 mV down to V _{TRIPMIN} - 250 mV
Note: Typical values are for 25°C and V _{DD} = 5.0V						

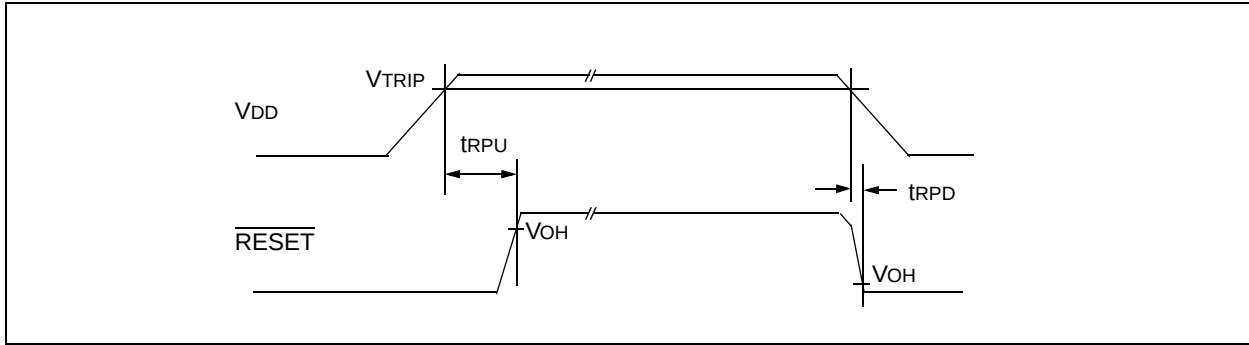


Figure 1-1: MCP120/130 Timing Diagram

MCP120/130

2.0 APPLICATIONS INFORMATION

2.1 The Need for Supervisory Circuits

For many of today's microcontroller applications, care must be taken to prevent low power conditions that can cause many different system problems. The most common causes are brown-out conditions where the system supply drops below the operating level momentarily, and the second, is when a slowly decaying power supply causes the microcontroller to begin executing instructions without enough voltage to sustain SRAM and producing indeterminate results.

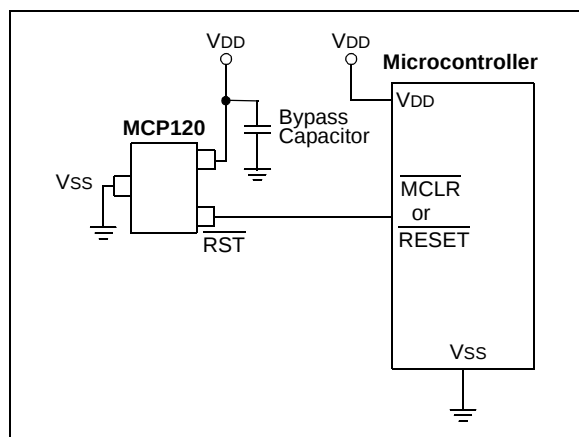


Figure 2-1: Typical Application

2.2 Negative Going V_{DD} Transients

Many system designers implementing POR circuits are concerned about the minimum pulse width required to cause a reset. Figure 2-2 shows typical transient voltage below the trip point ($V_{TRIP} - V_{DD}$) vs. transient duration. It shows that the farther below the trip point the transient pulse goes, the duration of the pulse required to cause a reset gets shorter. A 0.1 μF bypass cap mounted as close as possible to the V_{DD} pin provides additional transient immunity.

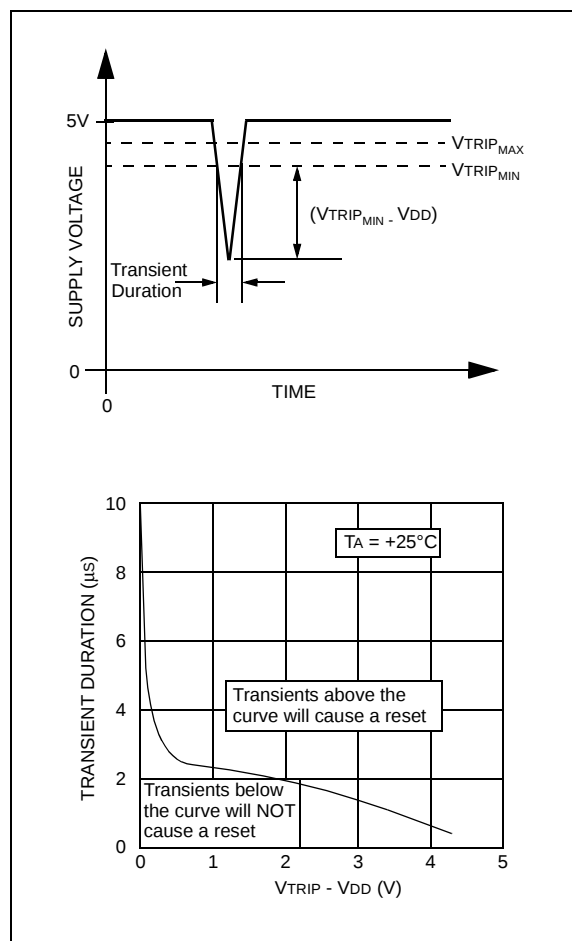


Figure 2-2: Typical Transient Response

2.3 Effect of Temperature on Timeout Period (t_{RPU})

The timeout period (t_{RPU}) determines how long the device remains in the reset condition. This is controlled by an internal RC timer and is effected by both V_{DD} and temperature. The graph shown in Figure 2-3 shows typical response for different V_{DD} values and temperatures.

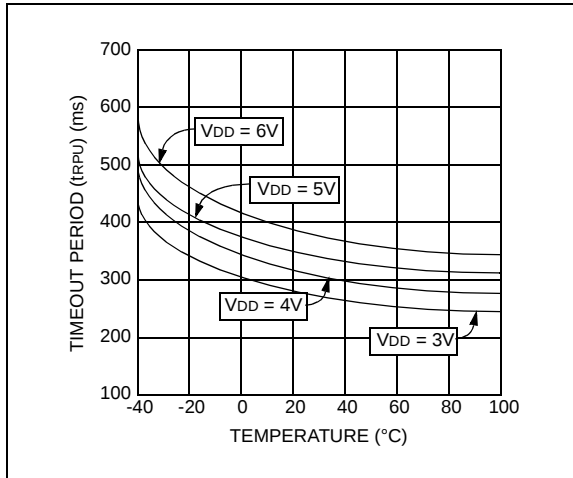


Figure 2-3: t_{RPU} vs. Temperature

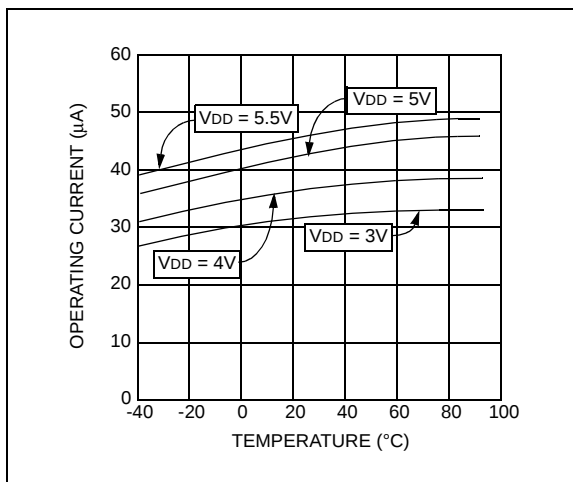


Figure 2-4: I_{DD} vs. Temperature

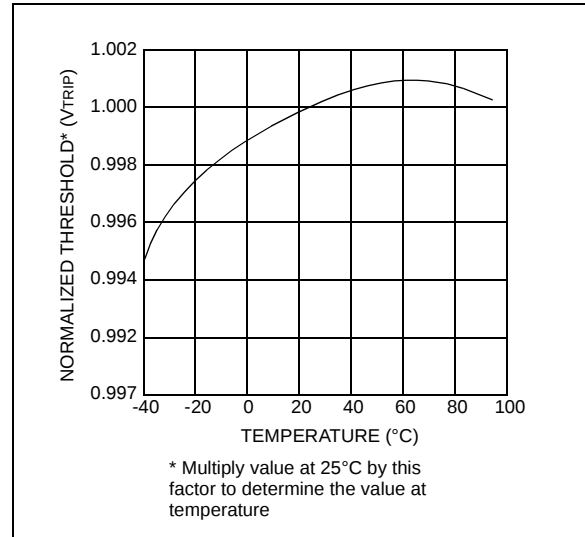


Figure 2-5: Normalized V_{TRIP} vs. Temperature

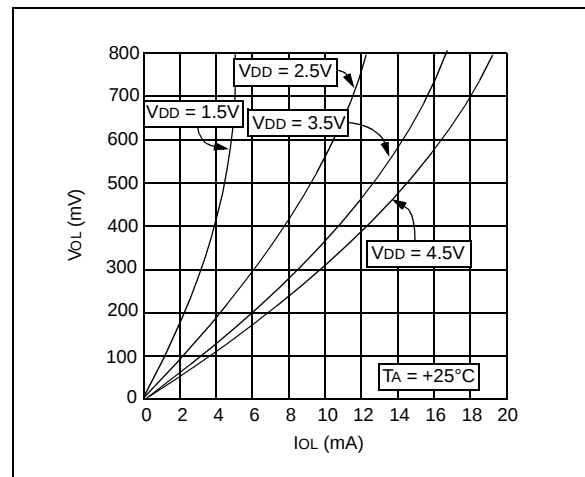


Figure 2-6: V_{OL} vs. I_{OL}

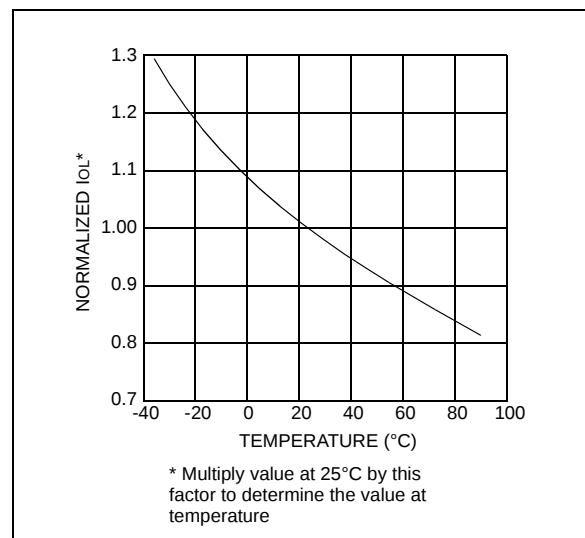


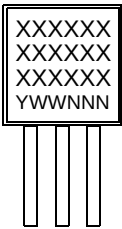
Figure 2-7: Normalized I_{OL} vs. Temperature

MCP120/130

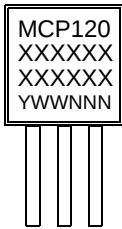
3.0 PACKAGING INFORMATION

3.1 Package Marking Information

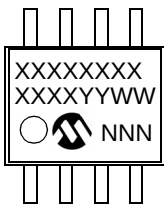
3-Lead Plastic Transistor Outline (TO-92)



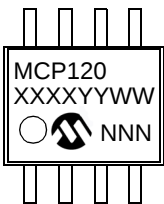
Example:



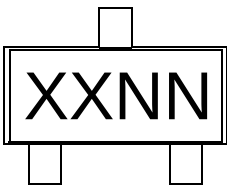
8-Lead Plastic Small Outline (SOIC)



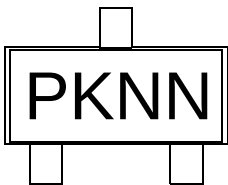
Example:



3-Lead Plastic Small Outline Transistor (SOT23)



Example:



SOT23 PARTS LABELING:

The table below identifies the first 2 characters (XX) in the 4-character field (XXNN) for marking of the 3-Lead SOT23 package.

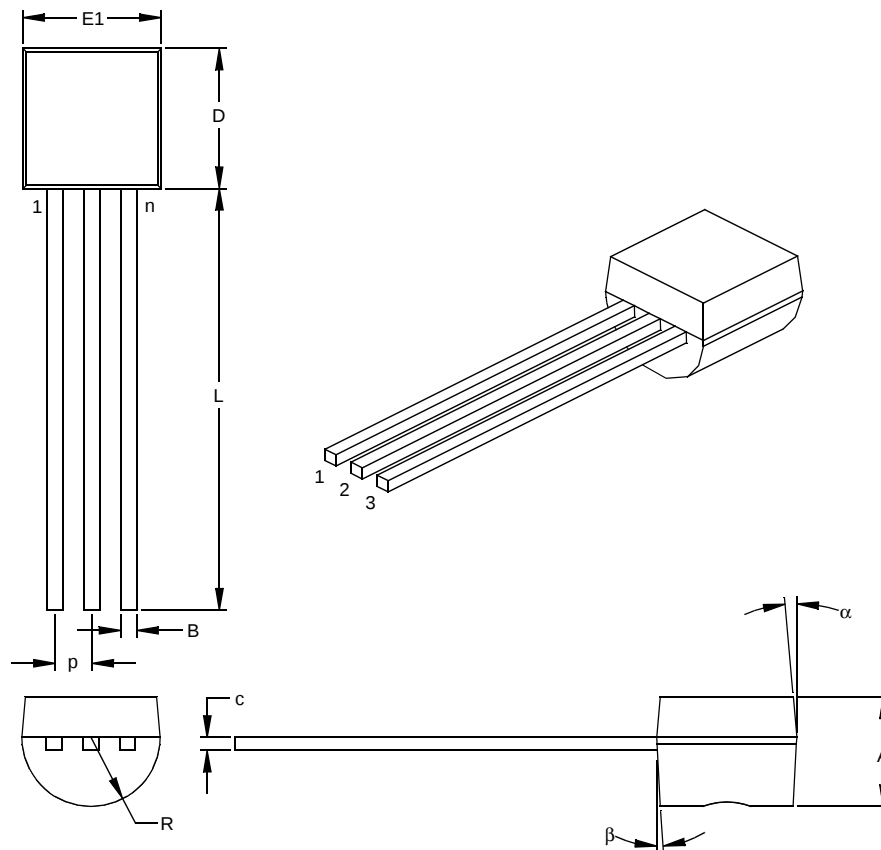
Mark	Part Number	Mark	Part Number
SJ	MCP120T-270I/TT	PJ	MCP130T-270I/TT
SK	MCP120T-300I/TT	PK	MCP130T-300I/TT
SL	MCP120T-315I/TT	PL	MCP130T-315I/TT
SM	MCP120T-450I/TT	PM	MCP130T-450I/TT
SN	MCP120T-460I/TT	PN	MCP130T-460I/TT
SO	MCP120T-475I/TT	PO	MCP130T-475I/TT
SP	MCP120T-485I/TT	PP	MCP130T-485I/TT

Legend:	XX...X	Customer specific information*
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.	

* Standard OTP marking consists of Microchip part number, year code, week code, and traceability code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

3.2 Package Detail Information

3-Lead Plastic Transistor Outline (TO) (TO-92)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		3			3	
Pitch	p		.050			1.27	
Bottom to Package Flat	A	.130	.143	.155	3.30	3.62	3.94
Overall Width	E1	.175	.186	.195	4.45	4.71	4.95
Overall Length	D	.170	.183	.195	4.32	4.64	4.95
Molded Package Radius	R	.085	.090	.095	2.16	2.29	2.41
Tip to Seating Plane	L	.500	.555	.610	12.70	14.10	15.49
Lead Thickness	c	.014	.017	.020	0.36	0.43	0.51
Lead Width	B	.016	.019	.022	0.41	0.48	0.56
Mold Draft Angle Top	α	4	5	6	4	5	6
Mold Draft Angle Bottom	β	2	3	4	2	3	4

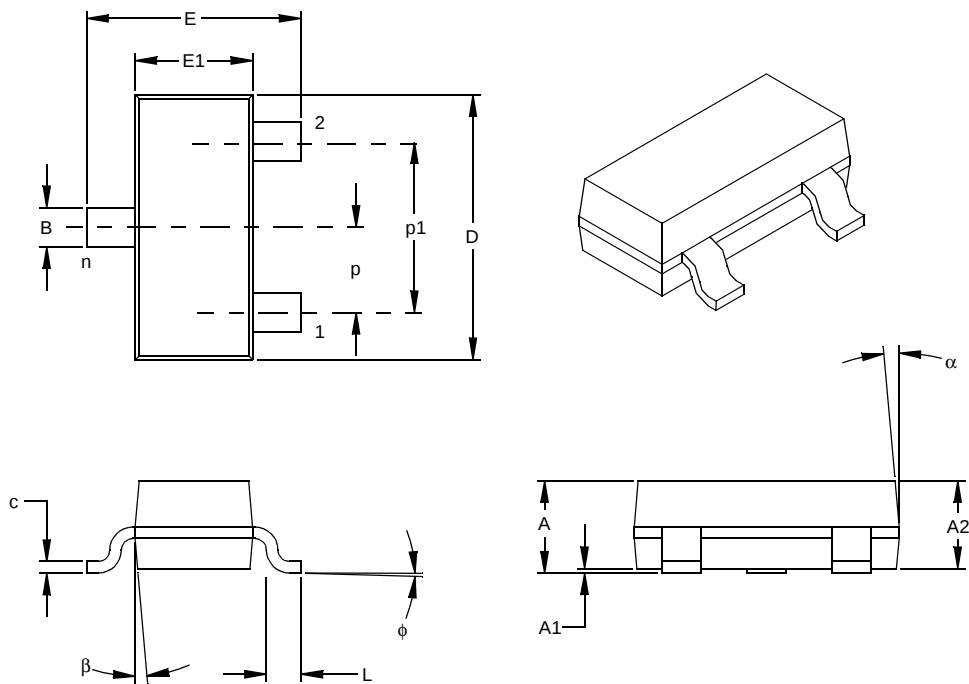
*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
JEDEC Equivalent: TO-92
Drawing No. C04-101

MCP120/130

3-Lead Plastic Small Outline Transistor (TT) (SOT23)

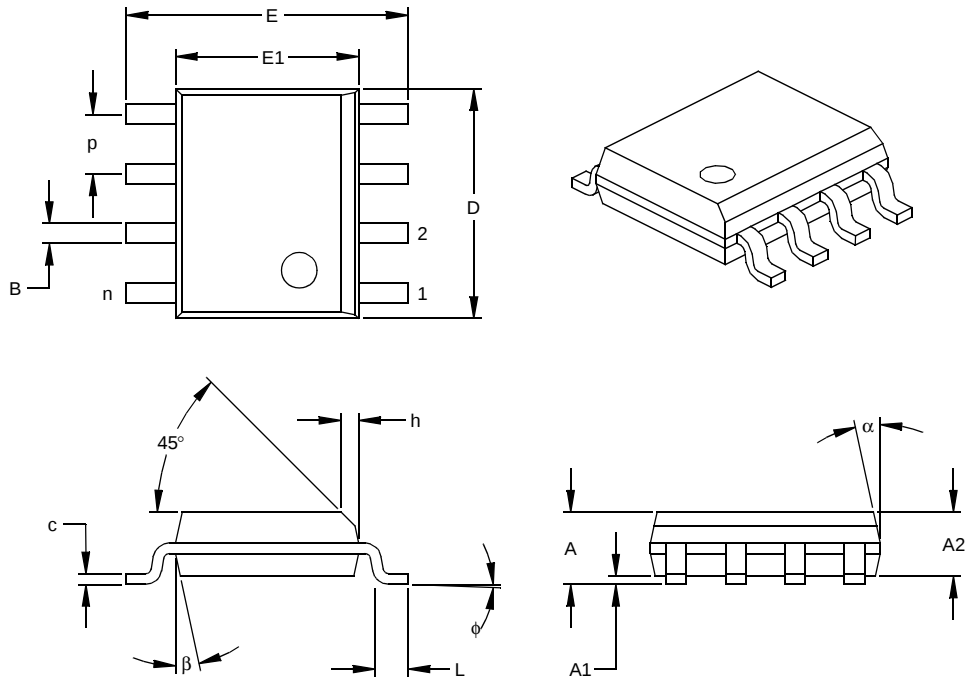


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		3			3	
Pitch	p		.038			0.96	
Outside lead pitch (basic)	p1		.076			1.92	
Overall Height	A	.035	.040	.044	0.89	1.01	1.12
Molded Package Thickness	A2	.035	.037	.040	0.88	0.95	1.02
Standoff §	A1	.000	.002	.004	0.01	0.06	0.10
Overall Width	E	.083	.093	.104	2.10	2.37	2.64
Molded Package Width	E1	.047	.051	.055	1.20	1.30	1.40
Overall Length	D	.110	.115	.120	2.80	2.92	3.04
Foot Length	L	.014	.018	.022	0.35	0.45	0.55
Foot Angle	φ	0	5	10	0	5	10
Lead Thickness	c	.004	.006	.007	0.09	0.14	0.18
Lead Width	B	.015	.017	.020	0.37	0.44	0.51
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
JEDEC Equivalent: TO-236
Drawing No. C04-104

8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
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Drawing No. C04-057

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NOTES:

NOTES:

MCP120/130

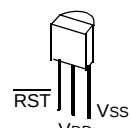
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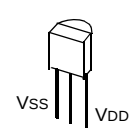
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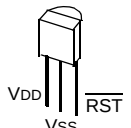
<u>PART NO.</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>XX</u>
Device	RESET/ RESET VTRIP Voltage	Bondout Option	Temperature Range	Package
Device:	MCP120: Supervisor circuit with open drain output MCP120T: Supervisor circuit with open drain output (tape & reel) MCP130: Supervisor circuit with open drain output and internal pull-up resistor MCP130T: Supervisor circuit with open drain output and internal pull-up resistor (tape & reel)			
RESET/RESET VTRIP Voltage	270 = $2.55 \leq V_{TRIP} \leq 2.70$ 300 = $2.85 \leq V_{TRIP} \leq 3.00$ 315 = $3.00 \leq V_{TRIP} \leq 3.15$ 450 = $4.25 \leq V_{TRIP} \leq 4.50$ 460 = $4.35 \leq V_{TRIP} \leq 4.60$ 475 = $4.50 \leq V_{TRIP} \leq 4.75$ 485 = $4.60 \leq V_{TRIP} \leq 4.85$			
Bondout Option: (TO-92 Only)	D = D Bond Option (see bond option chart) F = F Bond Option G = G Bond Option H = H Bond Option			
Temperature Range:	I = -40°C to $+85^{\circ}\text{C}$ (only offered in I)			
Package:	SN = SOIC (8-lead, 150 mil body) TO = TO-92 (3-lead) [offered in bags only] TT = SOT-23 (3-lead) [offered in tape & reel only]			

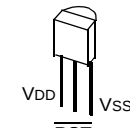
Examples:

- a) MCP120–270I/SN = VTRIP range of 2.55V - 2.70V, Industrial Temp., SOIC package
- b) MCP120–300DI/TO = VTRIP range of 2.85V - 3.00V, Bonding Option D, Industrial Temp., TO-92 package
- c) MCP120T–315I/TT = VTRIP range of 3.00V - 3.15V, Industrial Temp., SOT-23 package
- d) MCP130–450I/SN = VTRIP range of 4.25V - 4.50V, Industrial Temp., SOIC package
- e) MCP130–460FI/TO = VTRIP range of 4.35V - 4.60V, Bonding Option F, Industrial Temp., TO-92 package
- f) MCP130T–475I/TT = Tape & Reel, VTRIP range of 4.50V - 4.75V, Industrial Temp., SOT-23 package

**TO-92 with
'D' Bondout**
MCP120
MCP130

**TO-92 with
'F' Bondout**
MCP130

**TO-92 with
'G' Bondout**
MCP120

**TO-92 with
'H' Bondout**
MCP120
MCP130

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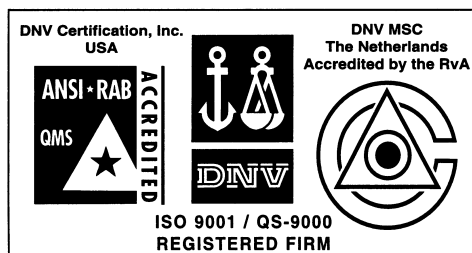
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01/30/01

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